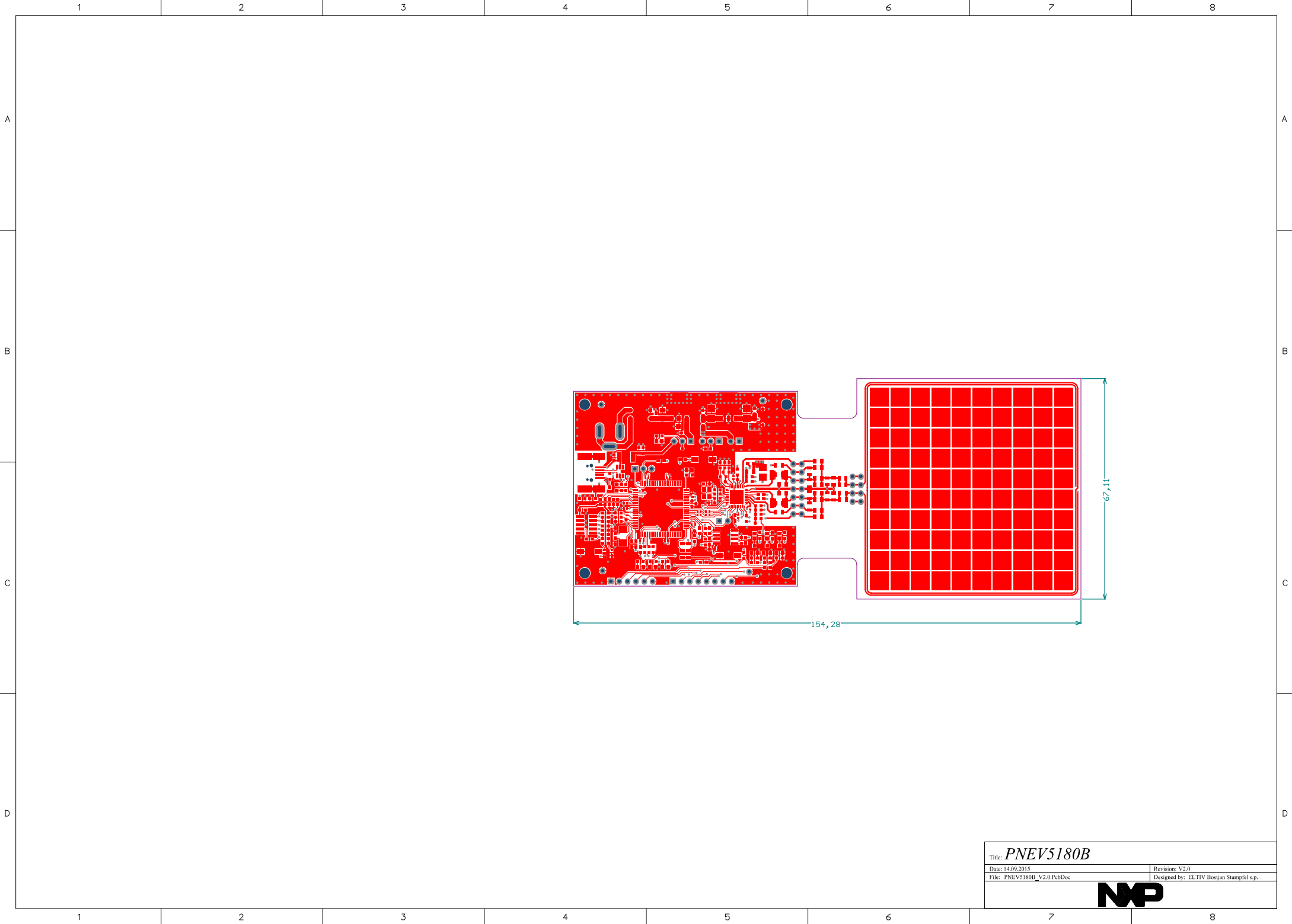
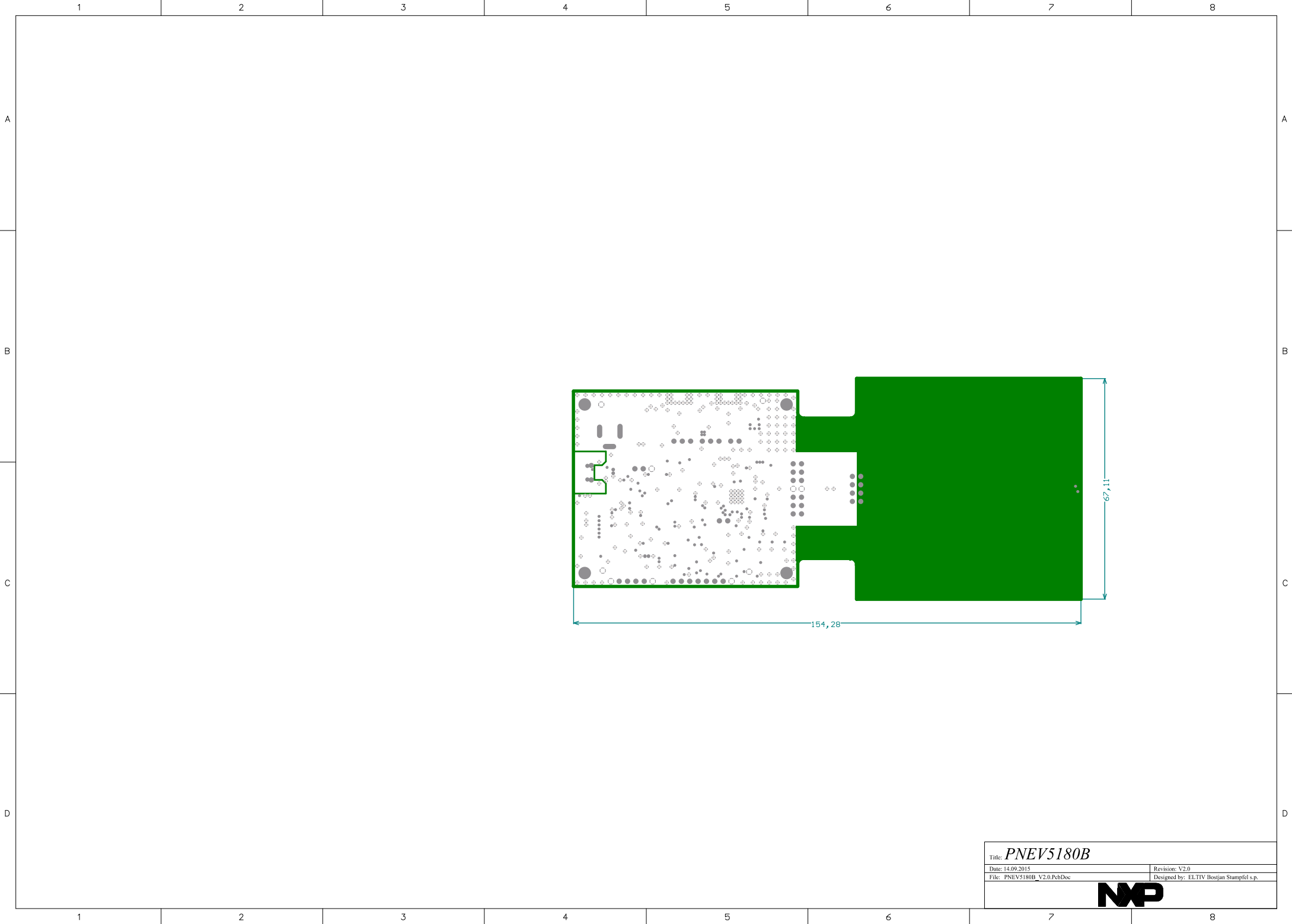
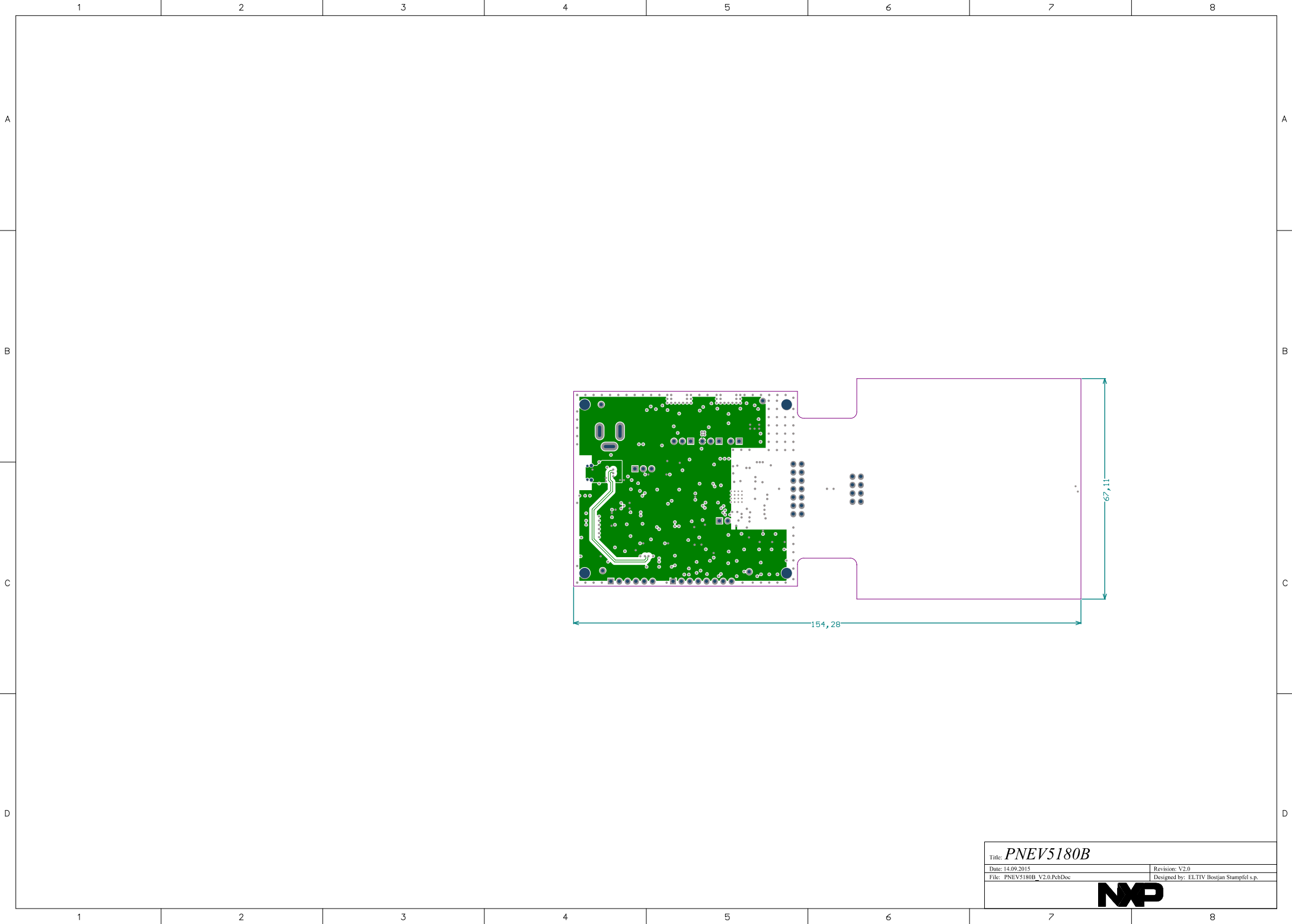




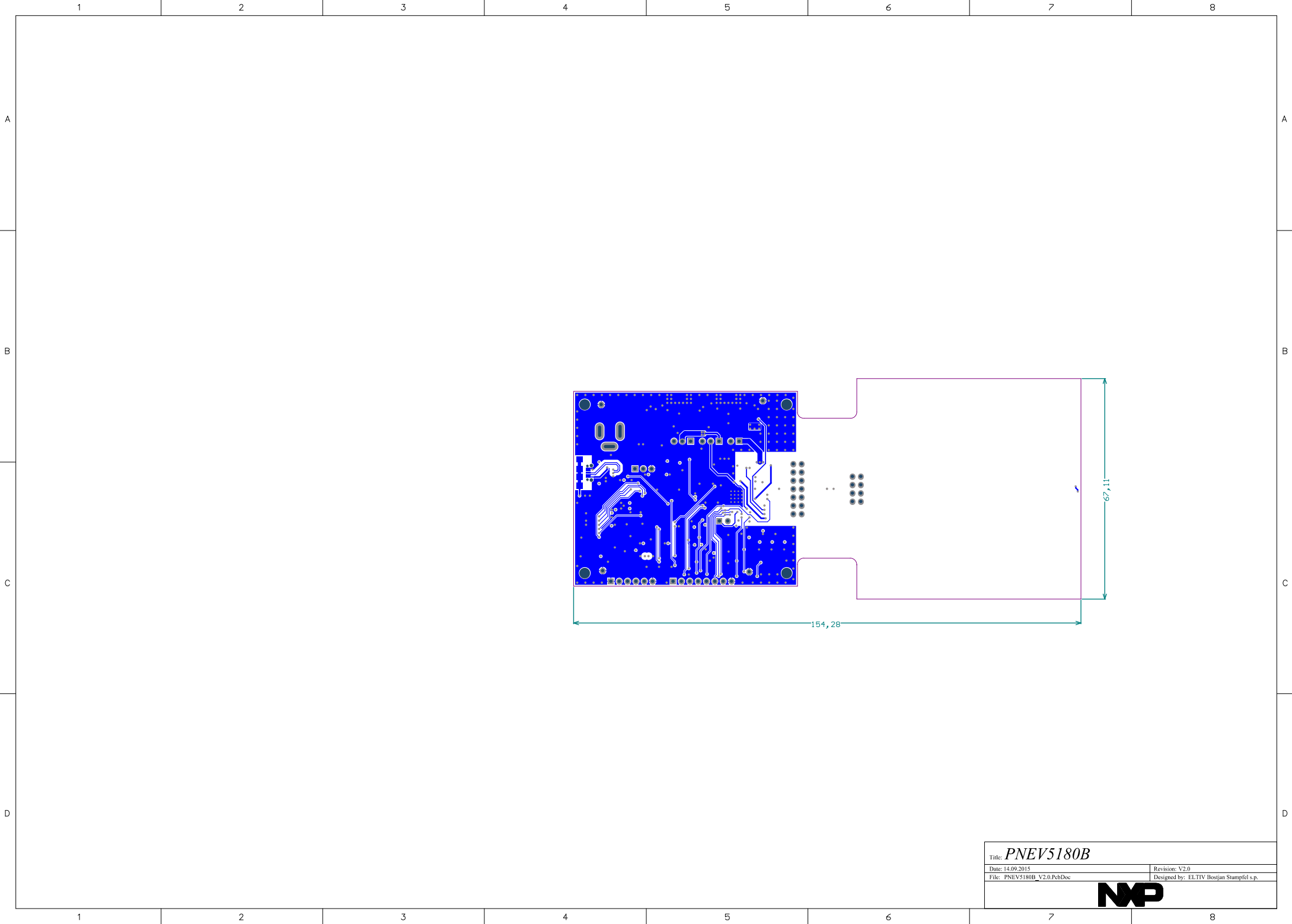
Title: <i>PNEV5180B</i>	
Date: 14.09.2015	Revision: V2.0
File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bosnjan Stumpfel s.p.
	



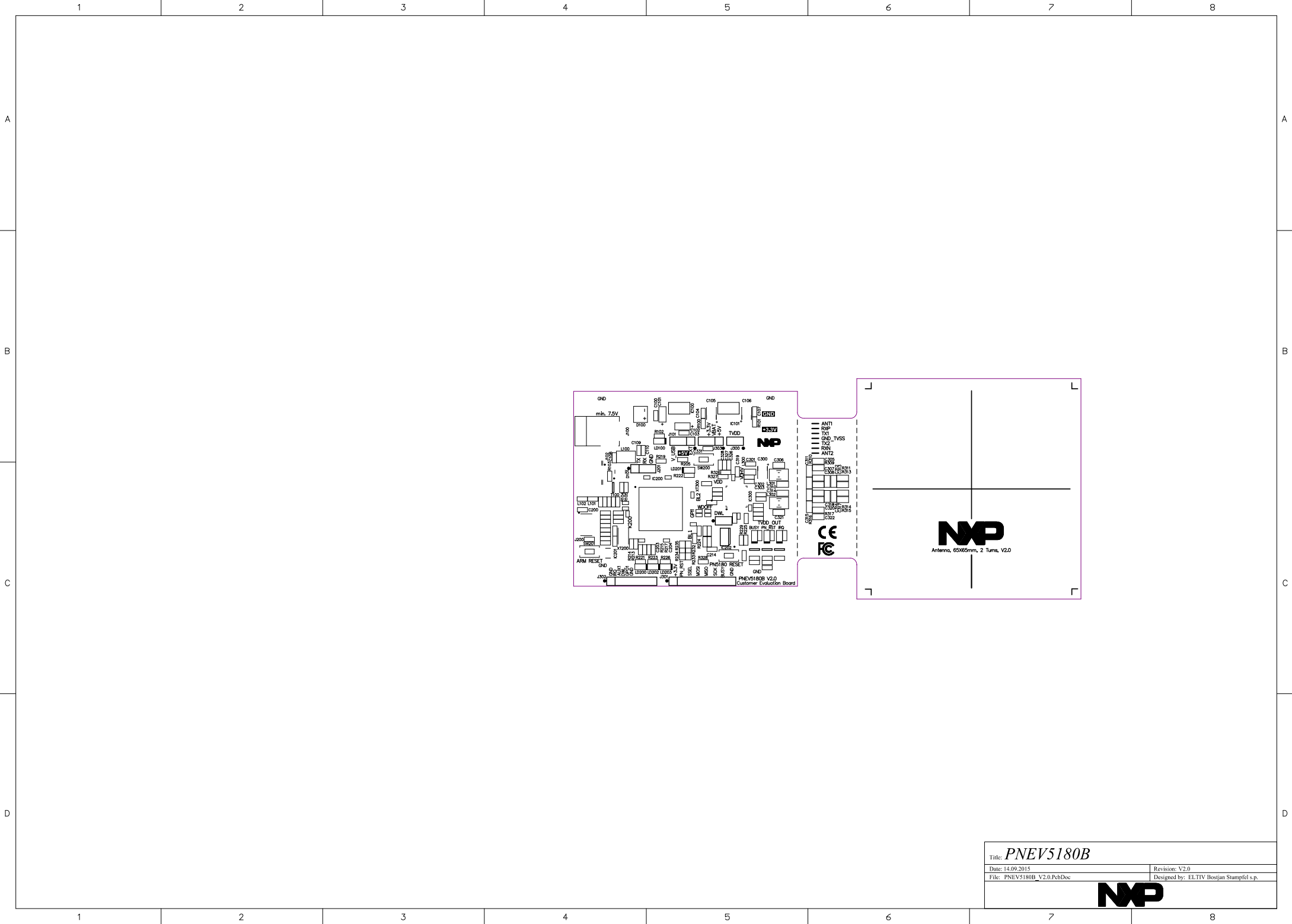
Title: <i>PNEV5180B</i>	
Date: 14.09.2015	Revision: V2.0
File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bosnian Stumpfel s.p.
	



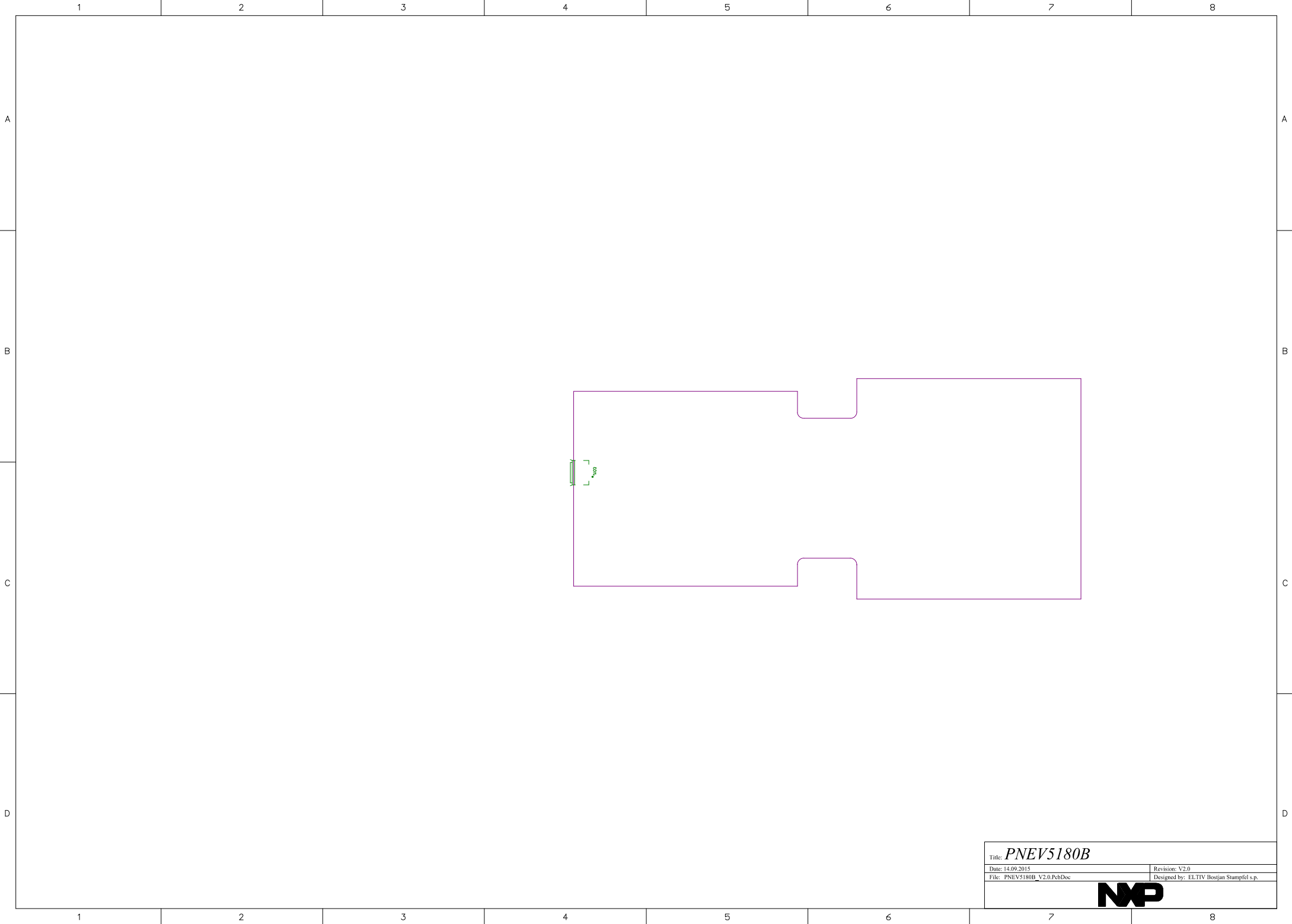
Title: <i>PNEV5180B</i>	
Date: 14.09.2015	Revision: V2.0
File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bosnjan Stumpfel s.p.
	



Title: <i>PNEV5180B</i>	
Date: 14.09.2015	Revision: V2.0
File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bosnjan Stumpfel s.p.
	



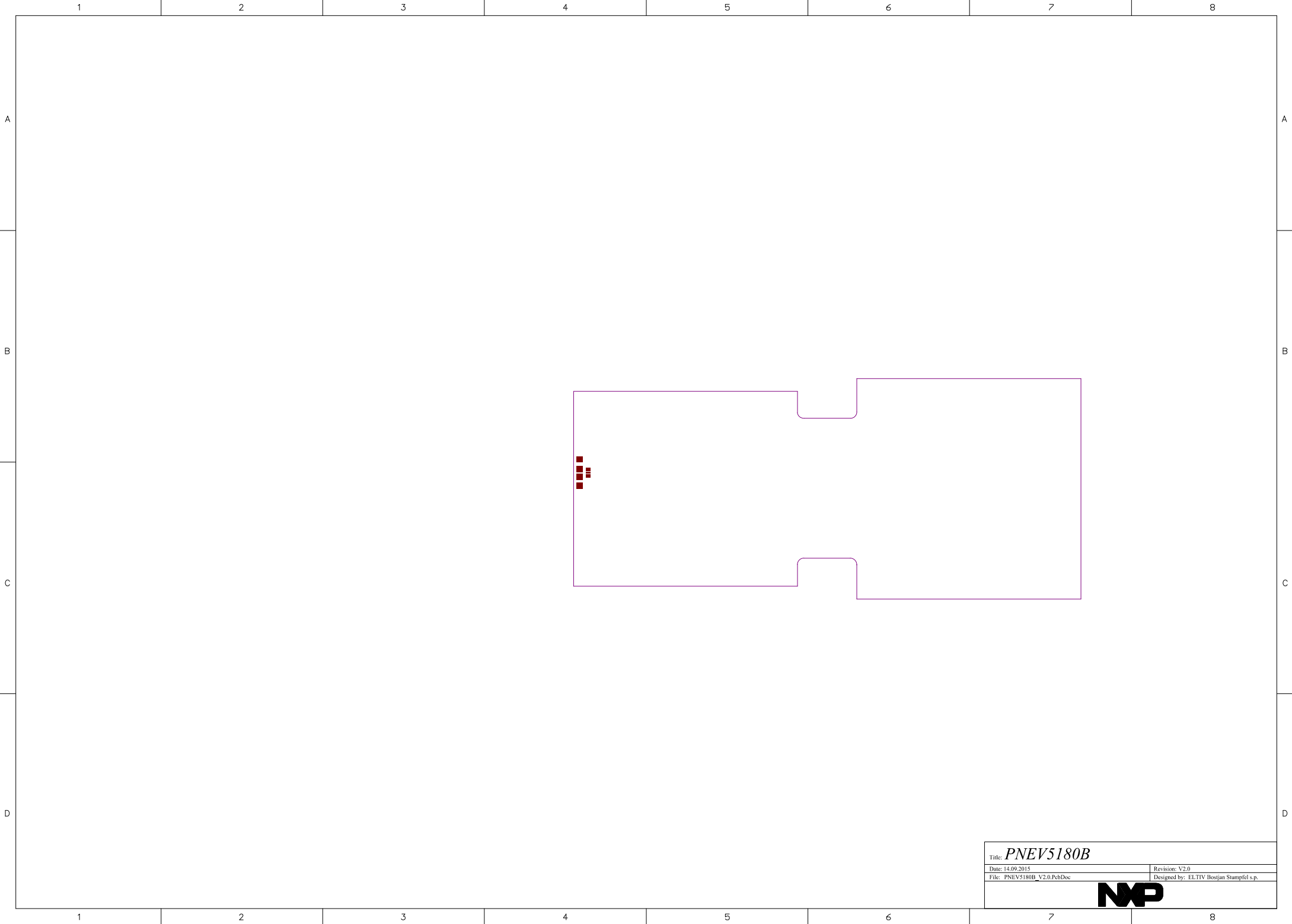
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Date: 14.09.2015	Revision: V2.0
File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bostjan Stumpfcl s.p.
	



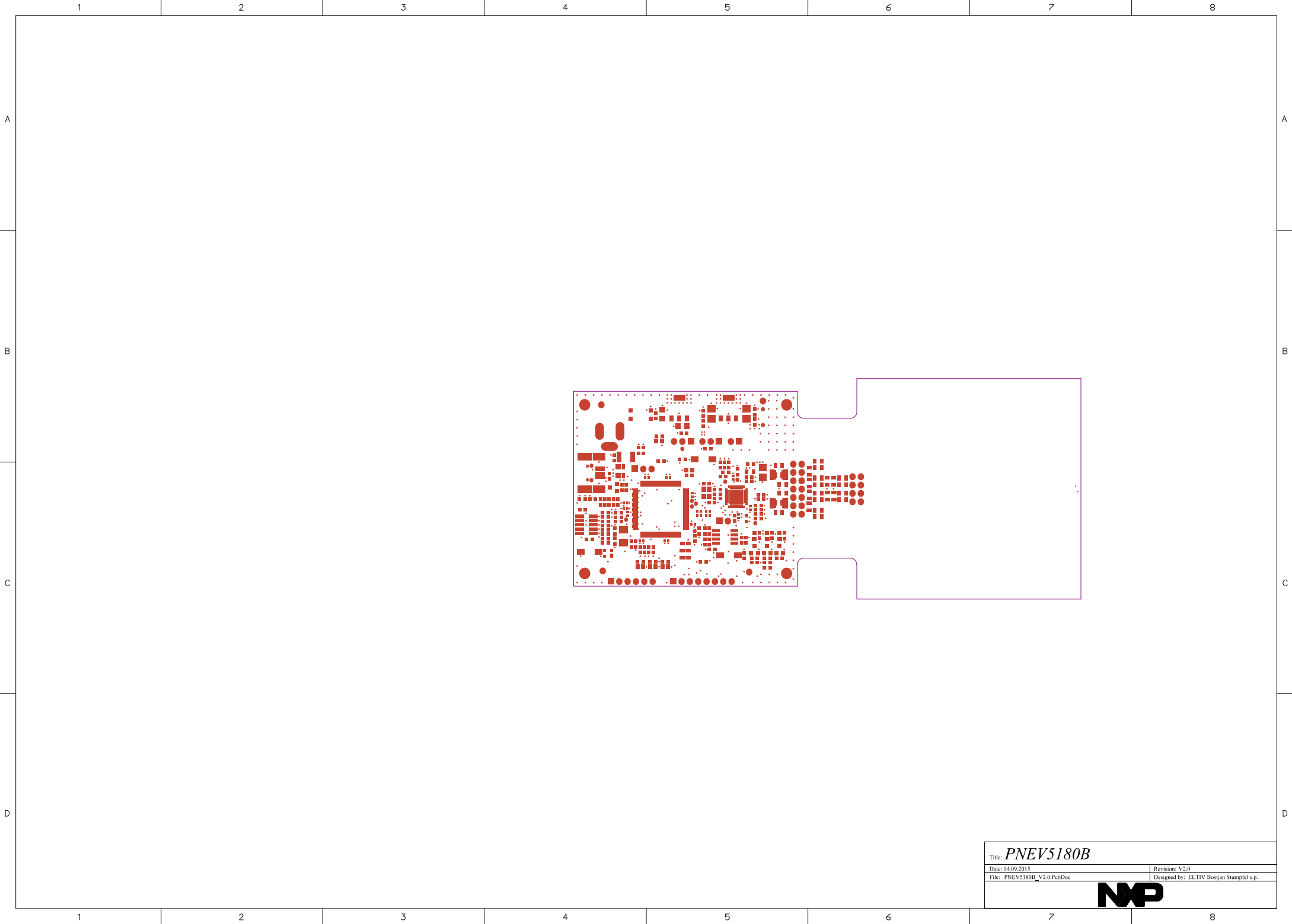
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Date: 14.09.2015	Revision: V2.0
File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bosnian Stumpfel s.p.
	



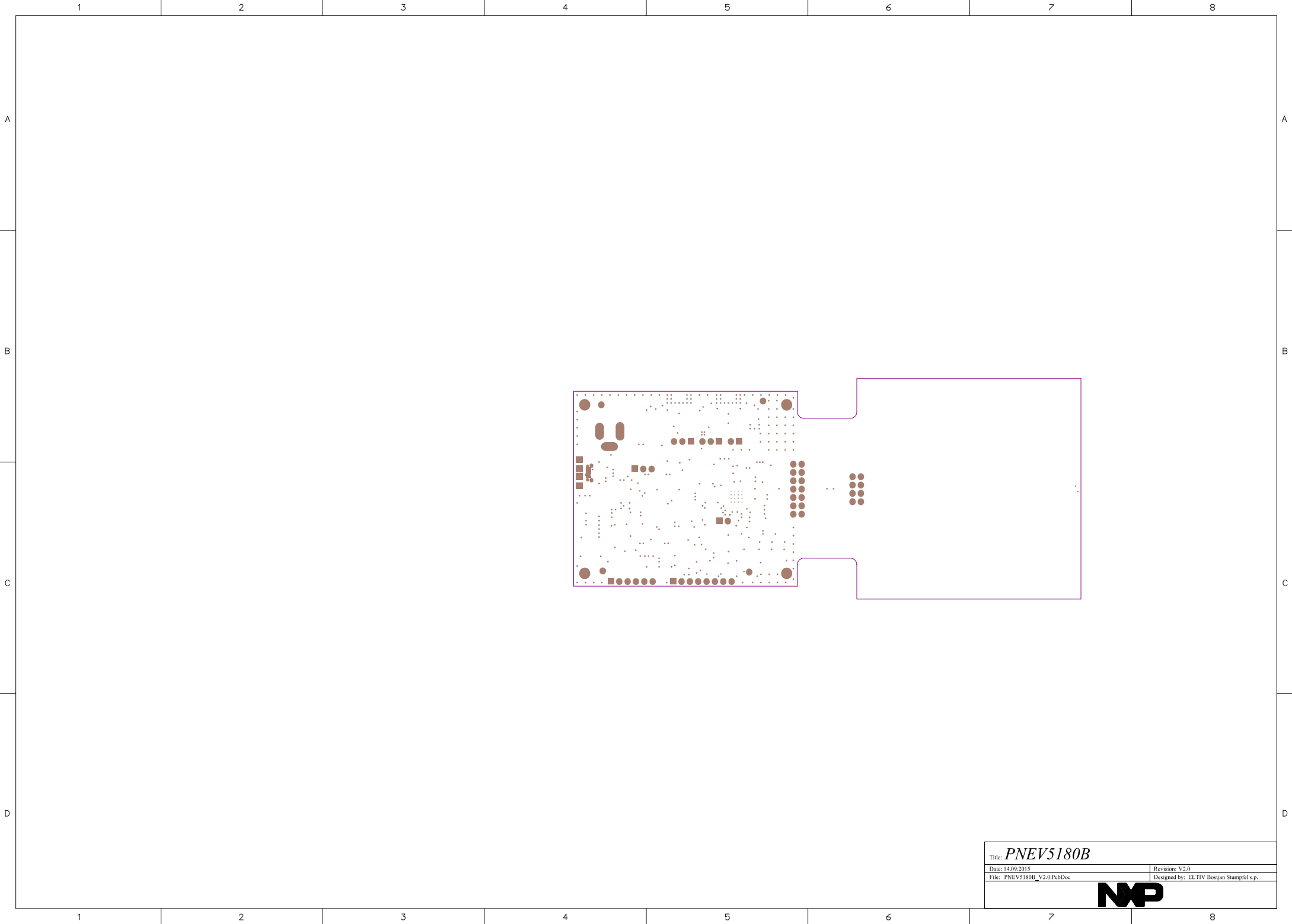
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Date: 14.09.2015	Revision: V2.0
File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bosnian Stumpfel s.p.
	



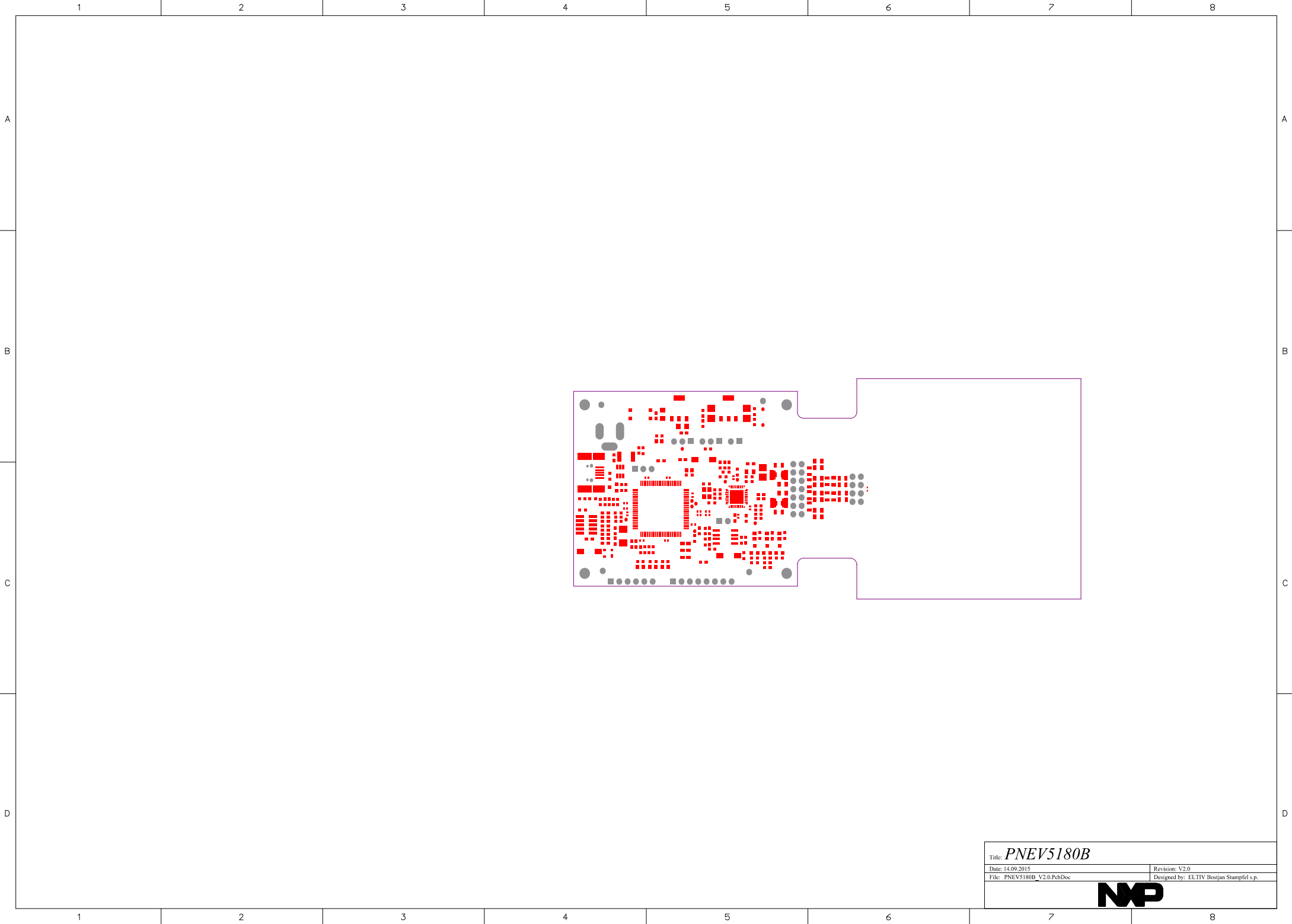
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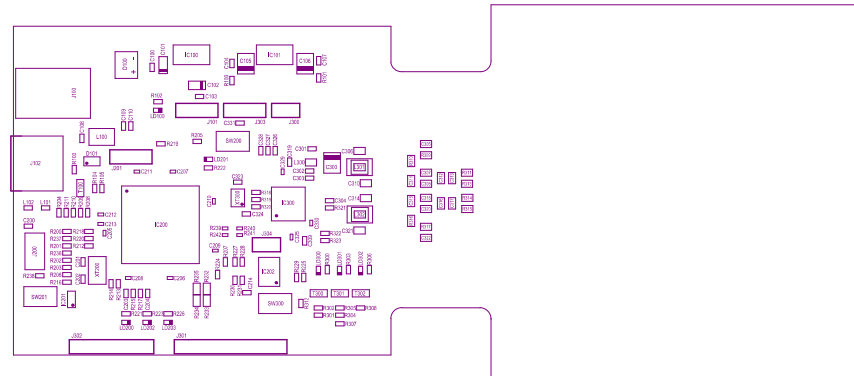
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File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bostjan Stumpfcl s.p.
	

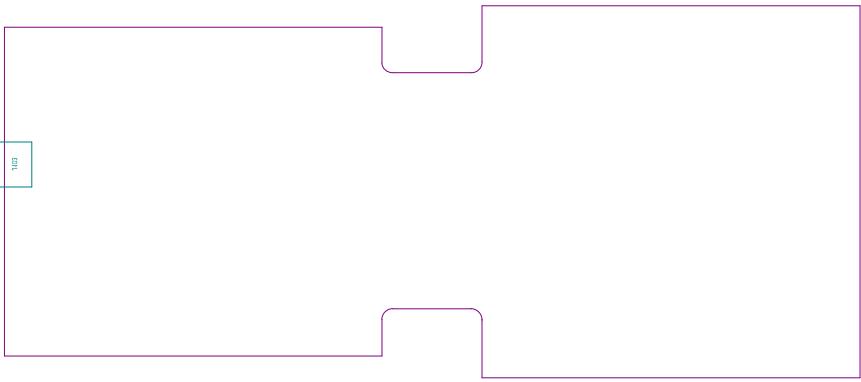


Title: <i>PNEV5180B</i>	
Date: 14.09.2015	Revision: V2.0
File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bostjan Stumpfcl s.p.
	



Title: <i>PNEV5180B</i>	
Date: 14.09.2015	Revision: V2.0
File: PNEV5180B_V2.0.PcbDoc	Designed by: ELTIV Bosnian Stumpfel s.p.
	





100

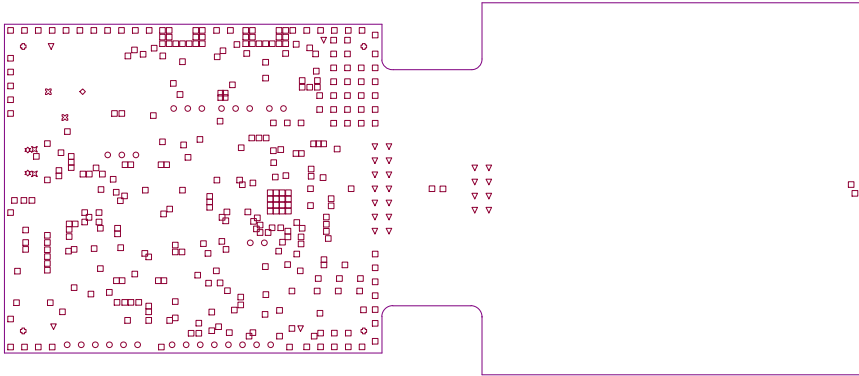
Master Drawings:

- material: FR4, Tg: 150
- thickness: 1,6mm (min 1,44, max 1,7mm)
- layer stackup: - Top Cu: 35um
 - prepreg 0,14mm
 - Internal Plane1 Cu: 35um
 - core 1,0mm
 - MidLayer1 Cu: 35um
 - prepreg 0,14mm
 - Bottom Cu: 35um
- min. hole metalization: 20um
- surface finishing: ENIG
- solder mask: - in accordance with IPC-SM-840
 - Liquid Photo Imageable (LPI)
 - color: GREEN
 - unless otherwise defined (in gerber), solder mask overlap on SMT pads is not allowed

- silk screen: Yes, White
- impedance control: Yes, see table below
- board must meet the acceptable level of IPC-A-600, Class 2, current revision.
- bow and twist: - max. 0.75% SMT boards
 - max. 1.5% THT boards
- point of origin (0,0): bottom left corner
- board is designed on 0.050 mm grid
- primary side: Top layer

Impedance table:

	Differential pair 90 [ohm] Width / Spacing [mm]
Layer1	0.22 / 0.3
Layer2	
Layer3	0.18 / 0.40
Layer4*	0.22 / 0.3



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
■	1	1,000mm (39,37mil)	PTH	Slot
▲	2	0,700mm (27,56mil)	NPTH	Round
●	2	1,000mm (39,37mil)	NPTH	Round
▽	2	1,000mm (39,37mil)	PTH	Slot
⊠	4	3,200mm (126,00mil)	NPTH	Round
⌘	26	1,000mm (39,37mil)	PTH	Round
○	27	1,016mm (40,00mil)	PTH	Round
○	346	0,300mm (11,81mil)	PTH	Round
	410 Total			

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Rout Path Length + Tool Size + Slot Length as defined in the PCB Layout